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January 2013

FJAFS1720

ESBC[™] Rated NPN Power Transistor

ESBC Features (FDS8817 MOSFET)

V _{CS(ON)}	I _C	Equiv. R _{CS(ON)}
0.304 V	10 A	$0.0304~\Omega^{~(1)}$

- · Low Equivalent On Resistance
- · Very Fast Switch: 150 kHz
- Squared RBSOA: Up to 1700 V
- Avalanche Rated
- · Low Driving Capacitance, No Miller Capacitance
- · Low Switching Losses
- Reliable HV Switch: No False Triggering due to High dv/dt Transients

Applications

- High-Voltage and High-Speed Power Switches
- Emitter-Switched Bipolar/MOSFET Cascode (ESBC[™])
- Smart Meters, Smart Breakers, SMPS, HV Industrial Power Supplies
- · Motor Drivers and Ignition Drivers

Description

The FJAFS1720 is a low-cost, high-performance power switch designed to provide the best performance when used in an ESBC[™] configuration in applications such as: power supplies, motor drivers, smart grid, or ignition switches. The power switch is designed to operate up to 1700 volts and up to 12 amps, while providing exceptionally low on-resistance and very low switching losses.

The ESBC $^{\text{TM}}$ switch is designed to be driven using off-the-shelf power supply controllers or drivers. The ESBC $^{\text{TM}}$ MOSFET is a low-voltage, low-cost, surface-mount device that combines low-input capacitance and fast switching, The ESBC $^{\text{TM}}$ configuration further minimizes the required driving power because it does not have Miller capacitance.

The FJAFS1720 provides exceptional reliability and a large operating range due to its square reverse-bias-safe-operating-area (RBSOA) and rugged design. The device is avalanche rated and has no parasitic transistors, so is not prone to static dv/dt failures.

The power switch is manufactured using a dedicated high-voltage bipolar process and is packaged in a high-voltage TO-3PF package.

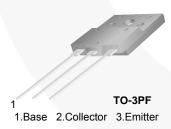


Figure 1. Pin Configuration

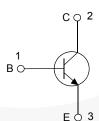


Figure 2. Internal Schematic Diagram

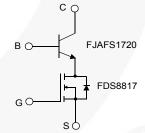


Figure 3. ESBC Configuration⁽²⁾

Ordering Information

Part Number	Marking	Package	Packing Method
FJAFS1720TU	J1720	TO-3PF	TUBE

Notes:

- 1. Figure of Merit.
- 2. Other Fairchild MOSFETs can be used in this ESBC application.

Absolute Maximum Ratings(3)

Values are at $T_A = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Value	Units
V_{CBO}	Collector-Base Voltage	1700	V
V_{CEO}	Collector-Emitter Voltage	800	V
V_{EBO}	Emitter-Base Voltage	6	V
I _C	Collector Current (DC)	12	Α
P_{C}	Collector Dissipation (T _C = 25°C)	60	W
T_J	Operating and Junction Temperature Range	-55 to +125	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C

Note:

3. Pulse Test is Pulse Width ≤ 5 ms, Duty Cycle ≤ 10%.

Thermal Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Max.	Units
$R_{\theta iC}$	Thermal Resistance, Junction to Case	2.08	°C/W

Electrical Characteristics(4)

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
I _{CES}	Collector Cut-off Current	V _{CB} = 1400 V, R _{BE} = 0	\		100	μΑ
I _{CBO}	Collector Cut-off Current	$V_{CB} = 800 \text{ V}, I_{E} = 0$			10	μΑ
I _{EBO}	Emitter Cut-off Current	$V_{EB} = 4 \text{ V, } I_{C} = 0$			100	μΑ
BV _{CBO}	Collector-Base Breakdown Voltage	$I_C = 500 \mu A, I_E = 0$	1700			V
BV _{CEO}	Collector-Emitter Breakdown Voltage	$I_C = 5 \text{ mA}, I_B = 0$	800			V
BV _{EBO}	Base-Emitter Breakdown Voltage	$I_E = 500 \mu A, I_C = 0$	6			V
h _{FE1}	DC Current Gain	V _{CE} = 5 V, I _C = 1 A	8.0			
h _{FE2}	DC Current Gain	V _{CE} = 5 V, I _C = 11 A	5.5		8.5	
		$I_C = 10 \text{ A}, I_B = 3.33 \text{ A}, h_{FE} = 3$		0.25		V
V _{CE} (sat)	Collector-Emitter Saturation Voltage	I _C = 5 A, I _B = 1.0 A, h _{FE} = 5	_/	0.20		V
		I _C = 1 A, I _B = 0.1 A, h _{FE} = 10		0.20		V
V _{BE} (sat)	Base-Emitter Saturation Voltage	I _C = 10 A, I _B = 3.33 A, h _{FE} = 3		0.86	<i>y</i>	V

Note:

4. Pulse Test: Pulse Width 5 ms, Duty Cycle 10%.

ESBC Configured Electrical Characteristics⁽⁵⁾

Values are at $T_A = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
f _T	Current Gain Bandwidth Product	$I_C = 0.1 \text{ A,V}_{CE} = 10 \text{ V}$		15		MHz
It _f	Inductive Current Fall Time	$V_{GS} = 10 \text{ V}, R_{G} = 47 \Omega,$		60		ns
t _s	Inductive Storage Time	V _{Clamp} = 500 V,		1000		ns
Vt _f	Inductive Voltage Fall Time	$I_C = 2 A$, $I_B = 0.2 A$, $h_{FE} = 10$		85		ns
Vt _r	Inductive Voltage Rise Time	$L_C = 1 \text{ mH},$		125		ns
t _c	Inductive Crossover Time	SRF = 350 kHz		165		ns
It _f	Inductive Current Fall Time	$V_{GS} = 10 \text{ V}, R_{G} = 47 \Omega,$		24		ns
t _s	Inductive Storage Time	V _{Clamp} = 500 V,		1500		ns
Vt _f	Inductive Voltage Fall Time	I _C = 5 A, I _B = 1 A, h _{FE} = 5		85		ns
Vt _r	Inductive Voltage Rise Time	L _C = 1 mH,		65		ns
t _c	Inductive Crossover Time	SRF = 350 kHz		110		ns
V _{CSW}	Maximum Collector Source Voltage at Turn-off without Snubber	h _{FE} = 5, I _C = 6 A	1700			٧
I _{GS(OS)}	Gate-Source Leakage Cur- rent	$V_{GS} = \pm 20 \text{ V}$		1.0		nA
		V_{GS} = 10 V, I_{C} = 10 A, I_{B} = 3.3 A, h_{FE} = 3		0.3040		V
		$V_{GS} = 10 \text{ V}, I_C = 6 \text{ A}, I_B = 2 \text{ A}, h_{FE} = 3$		0.2124		V
V _{CS(ON)}	Collector-Source On Voltage	$V_{GS} = 10 \text{ V}, I_C = 3 \text{ A}, I_B = 1 \text{ A}, h_{FE} = 3$		0.1362		V
		$V_{GS} = 10 \text{ V}, I_C = 3 \text{ A}, I_B = 0.6 \text{ A}, h_{FE} = 5$		0.1662		V
V _{GS(th)}	Gate Threshold Voltage	V _{BS} = V _{GS,} I _B = 250 μA		1.9		V
C _{iss}	Input Capacitance (V _{GS} = V _{CB} = 0)	V _{CS} = 25 V, f = 1 MHz		1805		pF
Q _{GS(tot)}	Gate-Source Charge V _{CB} =0	V_{GS} = 10 V, I_{C} = 6 A, V_{CS} = 25 V		6		nC
(()	Static Drain-Source	V _{GS} = 10 V, I _D = 15 A		5.4		mΩ
		14 4014 L 45 A T 405 00		7.5		
r _{DS(ON)}	On Resistance	V_{GS} = 10 V, I_{D} = 15 A, T_{A} = 125 °C		7.5		mΩ

Note:

5. Used typical FDS8817 MOSFET specifications in table. Table could vary if other Fairchild MOSFETs are used.

Typical Performance Characteristics

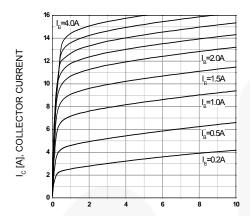


Figure 4. Static Characteristics

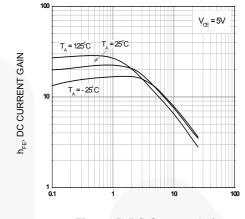


Figure 5. DC Current Gain

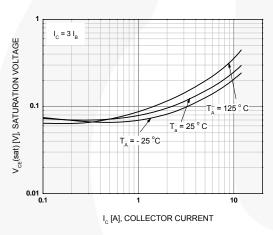


Figure 6. Collector-Emitter Saturation Voltage h_{FE} =3

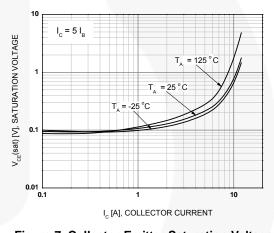


Figure 7. Collector-Emitter Saturation Voltage h_{FE}=5

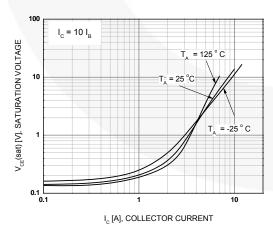


Figure 8. Collector-Emitter Saturation Voltage h_{FE} =10

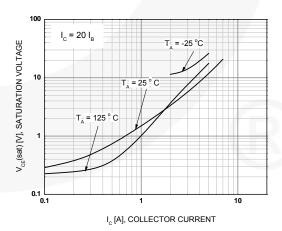


Figure 9. Collector-Emitter Saturation Voltage h_{FE} =20

Typical Performance Characteristics (Continued)

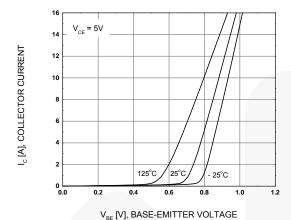


Figure 10. Base-Emitter On Voltage

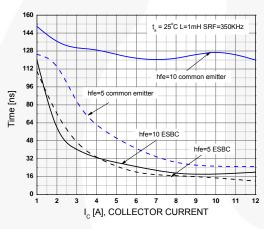


Figure 12. Inductive Load Collector Current Fall-time (t_f)

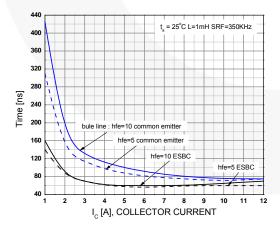


Figure 14. Inductive Load Collector Voltage Fall-time (t_f)

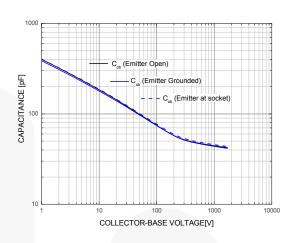


Figure 11. Capacitance

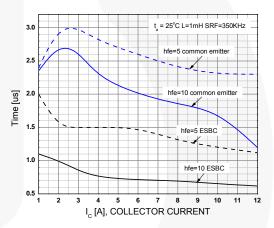


Figure 13. Inductive Load Collector Current Storage time (t_{stg})

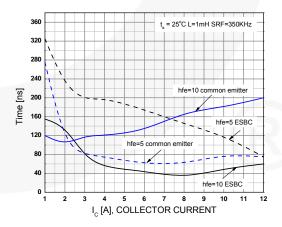


Figure 15. Inductive Load Collector Voltage Rise-time (t_r)

Typical Performance Characteristics (Continued)

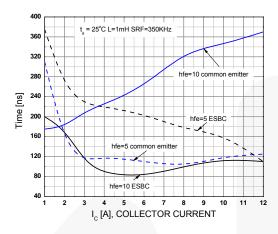


Figure 16. Inductive Load Collector Current / Voltage Crossover (t_c)

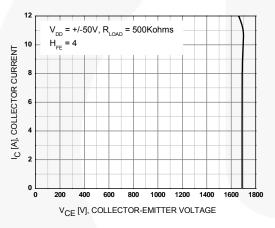


Figure 18. ESBC RBSOA

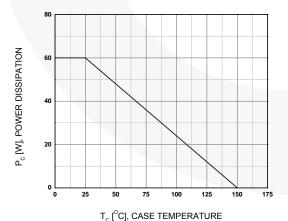


Figure 20. Power Derating

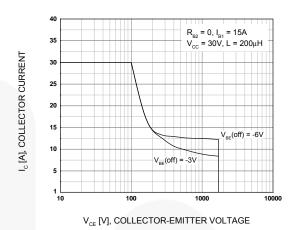


Figure 17. Reverse Bias Safe Operating Area

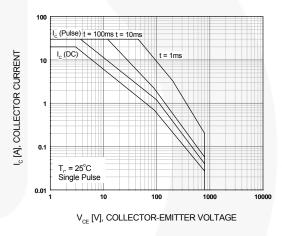


Figure 19. Forward Bias Safe Operating Area

Test Circuits

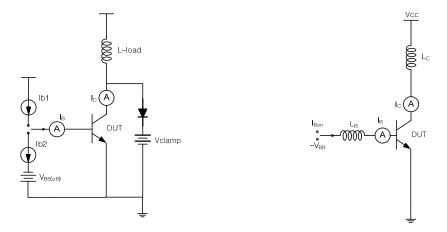


Figure 21. Test Circuit For Inductive Load and Reverse Bias Safe Operating

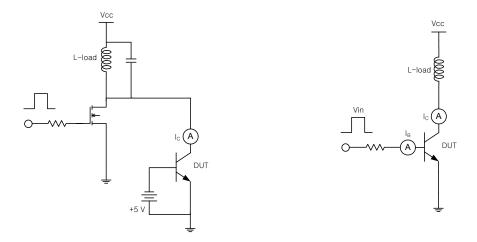


Figure 22. Energy Rating Test Circuit

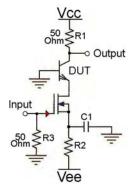


Figure 23. f_T Measurement

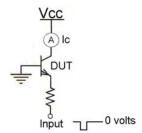


Figure 24. FBSOA

Test Circuits (Continued)

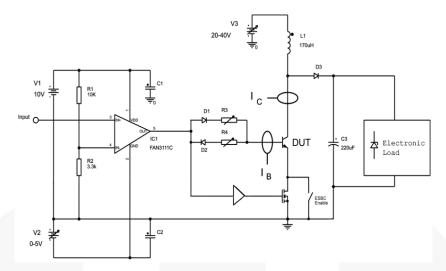


Figure 25. Simplified Saturated Switch Driver Circuit

Functional Test Waveforms

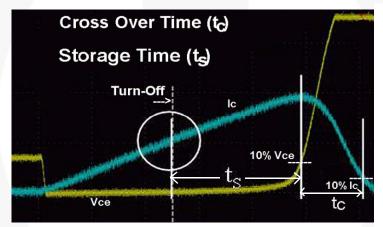


Figure 26. Crossover Time Measurement

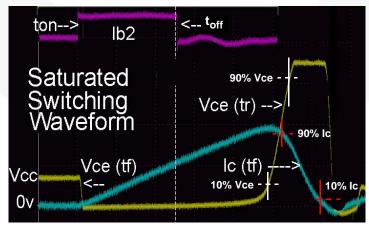


Figure 27. Saturated Switching Waveform

Functional Test Waveforms (Continued)

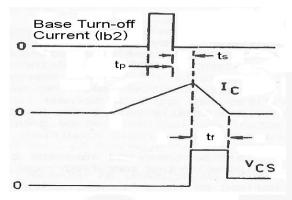


Figure 28. Storage Time - Common Emitter Base turn off (lb2) to I_C Fall-Time

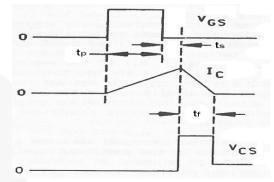
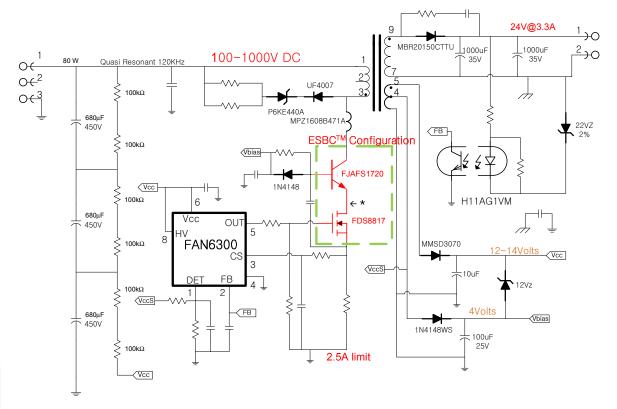


Figure 29. Storage Time - ESBC FET Gate (off) to I_C Fall-Time

Very Wide Input Voltage Range Supply

- 80 W; Secondary-Side Regulation: 3 Capacitor Input; Quasi Resonant



* Make short as possible

Driving ESBC Switches

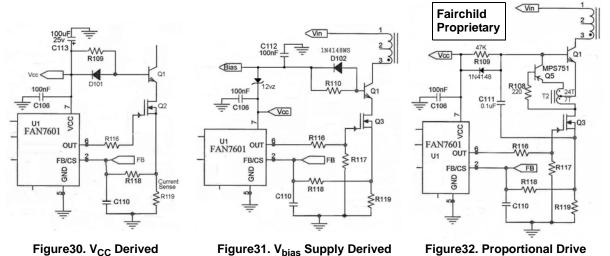


Figure31. V_{bias} Supply Derived

Figure 32. Proportional Drive

Physical Dimensions

TO-3PF

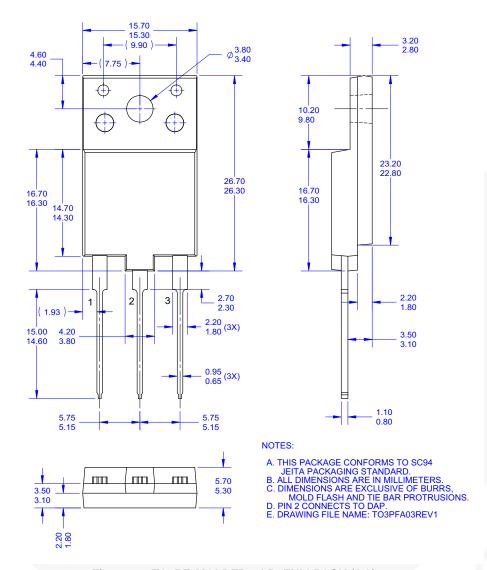


Figure 33. TO3PF, MOLDED, 3LD, FULLPACK (AG)

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